YEN-CHIEH (KEVIN) HUANG



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PROFESSIONAL SUMMARY

Semiconductor expert with over 15 years of experience in quality assurance, reliability engineering, and customer engagement across global markets. Proven ability to lead engineering teams, enhance product and process reliability, and ensure compliance with industry standards. Strong background in customer-facing roles, collaborating with major clients to resolve technical challenges and improve satisfaction. Renowned for expertise in product reliability, qualifications, and innovation in testing methodologies. A trusted advisor with a track record of research publications and patented contributions to the semiconductor field.

- My IEEE EDS talk: Chips, Character, and Keeping It Together

EDUCATION AND MEMBERSHIP

- IEEE Senior Member | 2023
- Completed three levels of Chartered Financial Analyst (CFA) Program, USA | 2008
- Master of Science in Physics, National Taiwan University (NTU), Taiwan | 2006
- Honorably discharged from the Army as a Second Lieutenant, ROCA | 2002
- Bachelor of Science in Physics, National Tsing Hua University (NTHU), Taiwan | 2000

PROFESSIONAL EXPERIENCE

Upright Financial Trust – New Jersey, USA

Chief Compliance Officer | Aug 2025 – Present

- Administering the Trust's compliance program under Rule 38a-1, and reporting to the Board on any material compliance matters.
- We oversee three SEC registered publicly listed mutual funds, UPUPX, UPDDX, and UPAAX.

Leverage Consulting – Taipei, Taiwan

System Development Engineer (AI/ML) | Jan 2025 – Present

- Architect scalable, secure, and resilient AI systems on cloud platforms.
- Translate high-level business goals into concrete architectural requirements, ensuring every AI initiative has a clear path from pilot to production.

Device Dynamics Lab – Hsinchu, Taiwan

Semiconductor Reliability Researcher | Jul 2023 – Present

- Developing GaN transistor reliability characterization methodology.
- Advising research direction for publication in GaN transistor communities.

Nordic Semiconductor – Hsinchu, Taiwan

Supply Chain Engineering Director | Jul 2022 – Jun 2023

- Managed a 40+ person team responsible for product engineering, qualifications, and hardware deployment.
- Oversaw the engineering activities of global suppliers (e.g., TSMC, GlobalFoundries, ASE, Amkor, iST).
- Streamlined the handshake processes from tape-out to final product qualification, driving quality and efficiency.

Product Qualification Manager | Jul 2020 – Jun 2022

- Led a team of 9 engineers to execute qualifications for all in-house products.
- Defined NPI qualification plans and introduced statistical analysis for data interpretation.
- Enhanced Si and package qualification capabilities of in-house reliability labs.

TSMC – Hsinchu, Taiwan

Technical Project Manager | Aug 2008 – Jun 2020

- Managed collaboration with process, design, and product teams for reliability and screening plans of NVM IP.
- Led automotive platform qualification, compliant with AEC-Q100 and ISO 26262 standards.
- Coordinated customer service and project management for major customer, Apple.

Nanya Technology Corporation – Taoyuan, Taiwan

Process Integration Engineer | Dec 2006 – Jul 2008

- Yield improvement for 70nm DDR2 deep trench DRAM RD integration.

KEY ACCOMPLISHMENTS

- According to the annual customer satisfaction surveys, Quality and Reliability are the number one reasons customers choose Nordic Semi products.
- Coordinated tsmc N16 Automotive Qualification which is the 1st Auto platform of tsmc.
- Managed tsmc N28 metal eFuse HTOL risk, ensuring on-time roll-out of technology.
- Designed test arrays for TDDB, boosting throughput by 10x for process qualification.

RECOMMENDATIONS

- Yung-Huei Lee – Retired Director, TSMC
- Ming-Han (Hank) Hsieh – Technical Manager, Google
- Ray Chang – Program Manager, Broadcom
- Kaustubh Joshi – Reliability R&D Engineer, INTEL
- Yulia Aksenton – Technologist, Apple

PAPERS & PATENTS - 19 Publications

- "Physical Model of Trapping-Induced Dynamic Degradation in GaN HEMT" (ISPSD 2025)
- "Excellent Radio Front-end Receiver Reliability of BLE SoC under RF-HTOL Stress Test" (IRPS 2023, Invited but declined)
- "A Novel On-Die GHz AC Stress Test Methodology for High-Speed IO Application" (IRPS 2017)
- US Patent: "Split Gate Structure and Method of Using the Same Diffusion" (2016)
- Full list of : Google Scholar: https://scholar.google.com/citations?hl=en&user=zki_i_gAAAAJ&view_op=list_works&sortby=pubdate